

85-131630/22 HITACHI CHEMICAL KK 26.09.83-JP-177652 (19.04.85) B32b-07/12	A81 G03 P73 (A18 A21)	HITB 26.09.83 *J6 0068-935-A	A(4-B4, 4-G7, 5-A1E1, 5-A1E2, 5-C1, 7-A4A, 7-A4B, 12-A5A, 4 2 12-A5B, 12-A5C, 12-E7A) G(3-B2B, 3-B2D2, 3-B2D3, 3-B2E1, 3-B2E2)
<p>Adhesive coated insulating plate - having thermosetting layer consisting of acrylonitrile butadiene rubber phenol and epoxy resin ethylene acetic acid vinyl copolymer</p>			
C85-057273			
<p>Thermosetting adhesive layer consisting of acrylonitrile but butadiene rubber, phenol resin, epoxy resin and ethylene acetic acid vinyl copolymer is formed on the surface of plate. Adhesive is an adhesive made up by uniformly mixing 25-80 wt. pt. acrylonitrile butadiene rubber, 10-55 wt. pt. phenol resin, 2-45 wt. pt. epoxy resin and 0.5-15 wt.pt. ethylene acetic acid vinyl copolymer with organic solvent. Or it is made by uniformly mixing 30-50 wt.pt. acrylonitrile butadiene rubber, 15-45 wt.pt. alkylphenol, 5-24 wt. pt. epoxy resin, 1-16 wt. pt. ethylene acid vinyl copolymer and 10-45 wt. pt. inorganic filler with organic solvent.</p>			
<p>USE/ADVANTAGE - Provides plate used for mfg. a printed wiring plate forming a metal conductor circuit by means of electroless plating (5pp Dwg.No.0/0)</p>			

© 1985 DERWENT PUBLICATIONS LTD.

128, Theobalds Road, London WC1X 8RP, England

US Office: Derwent Inc. Suite 500, 6845 Elm St. McLean, VA 22101

Unauthorised copying of this abstract not permitted.